

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of:

TONGBI JIANG  
EDWARD SCHROCK



Serial No.: 09/258,961

ART UNIT: 2811

Filing Date: March 1, 1999

Examiner: PAREKH, N.

Title: BGA PACKAGE HAVING SUBSTRATE WITH  
PATTERNED SOLDER MASK DEFINING OPEN  
DIE ATTACH AREA (AS AMENDED)

Attorney Docket No.: 98-0645.1

#12/C  
1-23-01  
afx

**PRELIMINARY AMENDMENT  
SUBMITTED WITH CPA APPLICATION  
UNDER 37 CFR 1.53(d)  
January 12, 2001**

RECEIVED  
JAN 18 2001  
TC 2800 MAIL ROOM

Assistant Commissioner for Patents  
BOX CPA  
Washington, D.C. 20231

Sir:

This Preliminary Amendment is submitted with a Continued Prosecution Application (CPA) being filed under 37 CFR 1.53(d).

This Amendment is in response to the Office Action dated October 13, 2000 having a statutory period for response set to expire on January 16, 2001. Please amend the captioned case as follows.

**In the claims:**

Please amend claims 24-36. A clean version of the amended claims follows. In addition, a marked version of the amended claims showing the changes follows the Remarks section.